

AIXTRON: Major Asian display manufacturer purchases system for the deposition of OLED barrier films

First order for recently acquired innovative technology

Herzogenrath/Germany, September 09, 2015 – AIXTRON SE (FSE: AIXA; NASDAQ: AIXG), a worldwide leading provider of deposition equipment to the semiconductor industry, has sold the first OPTACAP™-200 encapsulation tool to a major Asian display manufacturer. The standalone R&D system that handles substrate sizes of 200 mm x 200 mm was ordered in the third quarter 2015 and is scheduled for delivery in the first quarter 2016.

The innovative OPTACAP™ plasma enhanced chemical vapor deposition (PECVD) technology enables the deposition of highly flexible and effective barrier films for thin-film encapsulation of OLED display, OLED lighting, organic photovoltaic and flexible electronic devices.

“Thin-film encapsulation is an essential step within the OLED manufacturing process. Therefore, we are delighted to be able to provide an innovative solution to the industry which delivers excellent barrier films at high throughput. Therefore, this solution contributes to a significant reduction of manufacturing costs for the critical encapsulation process step within the production of flexible as well as rigid OLED devices”, says Andreas Toennis, Chief Technology Officer of AIXTRON SE.

The groundbreaking OPTACAP™ encapsulation technology has been the main driver for AIXTRONs acquisition of Silicon Valley-based Company PlasmaSi, Inc. in April 2015. The full integration of the technology into AIXTRONs already existing OLED activities is part of the company’s incorporation into the AIXTRON Group.

About AIXTRON

AIXTRON SE is a worldwide leading provider of deposition equipment to the semiconductor industry. The Company was founded in 1983 and is headquartered in Herzogenrath (near Aachen), Germany, with subsidiaries and sales offices in Asia, United States and in Europe. AIXTRON’s technology solutions are used by a diverse range of customers worldwide to build advanced components for electronic and opto-electronic applications based on compound, silicon, or organic semiconductor materials. Such components are used in a broad range of innovative applications, technologies and industries. These include LED applications, display technologies, data storage, data transmission, energy management and conversion, communication, signaling and lighting as well as a range of other leading-edge technologies.

Our registered trademarks: AIXACT®, AIXTRON®, Atomic Level SolutionS®, Close Coupled Showerhead®, CRIUS®, Gas Foil Rotation®, OVPD®, Planetary Reactor®, PVPD®, TriJet®, Optacap™

For further information on AIXTRON (FSE: AIXA, ISIN DE000A0WMPJ6; NASDAQ: AIXG, ISIN US0096061041) please visit our website at: www.aixtron.com.

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